

20P03 Datasheet

P-Channel 30-V (D-S) MOSFET

PRODUCT SUMMARY						
V _{DS} (V)	$R_{DS(on)}\left(\Omega\right)$	I _D (A) ^d	Q _g (Typ.)			
- 30	0.033 at V _{GS} = - 10 V	- 38	19 nC			
- 30	0.046 at V _{GS} = - 4.5 V	- 25	19110			

FEATURES

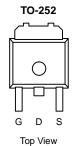
- · Halogen-free
- TrenchFET® Power MOSFET
- 100 % R_g Tested
- 100 % UIS Tested

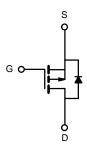


ROHS

APPLICATIONS

- Load Switch
- Notebook Adaptor Switch





P-Channel MOSFET

Parameter	Symbol	Limit	Unit	
Drain-Source Voltage	V _{DS}	- 30	V	
Gate-Source Voltage	V _{GS}	± 20	V	
	T _C = 25 °C		- 38	
Continuous Drain Current (T _{.1} = 150 °C)	T _C = 70 °C		- 25	
Continuous Diam Current (1) = 130 °C)	T _A = 25 °C	I _D	- 14.9 ^{a, b}	
	T _A = 70 °C	1	- 13.6 ^{a, b}	
Pulsed Drain Current	<u>.</u>	I _{DM}	- 112	A
Continuous Source-Drain Diode Current	T _C = 25 °C		- 4.1	
Continuous Source-Drain Diode Current	T _A = 25 °C	ls –	- 2.2 ^{a, b}	
Avalanche Current	1 0411	I _{AS}	- 20	
Single-Pulse Avalanche Energy	L = 0.1 mH	E _{AS}	20	mJ
	T _C = 25 °C		25	
Manianum Danian Disain ation	T _C = 70 °C		20	W
Maximum Power Dissipation	T _A = 25 °C	P _D	2.7 ^{a, b}	VV
	T _A = 70 °C		1.7 ^{a, b}	
Operating Junction and Storage Temperature Range	T _J , T _{stg}	- 55 to 150	°C	

THERMAL RESISTANCE RATINGS						
Parameter		Symbol	Typical	Maximum	Unit	
Maximum Junction-to-Ambient ^{a, c}	t ≤ 10 s	R _{thJA}	38	46	°C/W	
Maximum Junction-to-Foot	Steady State	R _{th,IF}	20	25		

Notes:

- a. Surface mounted on 1" x 1" FR4 board.
- b. t = 10 s.
- c. Maximum under Steady State conditions is 85 °C/W.
- d. Based on T_C = 25 °C.



Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit
Static						
Drain-Source Breakdown Voltage	V_{DS}	$V_{GS} = 0 \text{ V}, I_D = -250 \mu\text{A}$	- 30			V
V _{DS} Temperature Coefficient	$\Delta V_{DS}/T_{J}$	I _D = - 250 μA		- 34		mV/
V _{GS(th)} Temperature Coefficient	$\Delta V_{GS(th)}/T_J$	ι _D = - 250 μΑ		5.3		°C
Gate-Source Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}, I_{D} = -250 \mu A$	- 1.0		- 2.5	V
Gate-Source Leakage	I _{GSS}	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 25 \text{ V}$			± 100	nA
Zara Cata Valtaga Drain Current		V _{DS} = - 30 V, V _{GS} = 0 V V _{DS} = - 30 V, V _{GS} = 0 V, T _J = 55 °C			- 1	μA
Zero Gate Voltage Drain Current	I _{DSS}				- 5	
On-State Drain Current ^a	I _{D(on)}	$V_{DS} \ge -10 \text{ V}, V_{GS} = -10 \text{ V}$	- 30			Α
5 . 6 . 6	Р	V _{GS} = - 10 V, I _D = - 10 A		0.033		
Drain-Source On-State Resistance ^a	R _{DS(on)}	V _{GS} = - 4.5 V, I _D = - 8 A		0.046		Ω
Forward Transconductance ^a	9 _{fs}	V _{DS} = - 10 V, I _D = - 10 A		28		S
Dynamic ^b						
Input Capacitance	C _{iss}			1350		
Output Capacitance	C _{oss}	$V_{DS} = -15 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$		255		pF
Reverse Transfer Capacitance	C _{rss}			190		
Total Gate Charge	Q_g $V_{DS} = -15 \text{ V}, V_{GS} = -10 \text{ V}, I_D = -10 \text{ A}$	V _{DS} = - 15 V, V _{GS} = - 10 V, I _D = - 10 A		27	43	1
			19	25	nC	
Gate-Source Charge	Q _{qs}	V _{DS} = - 15 V, V _{GS} = - 4.5 V, I _D = - 10 A		6		
Gate-Drain Charge	Q _{gd}			12		1
Gate Resistance	R_g	f = 1 MHz	0.5	2.2	4.4	Ω
Turn-On Delay Time	t _{d(on)}			13	25	
Rise Time	t _r			12	24	
Turn-Off DelayTime	t _{d(off)}	$I_D \cong$ - 10 A, V_{GEN} = - 10 V, R_g = 1 Ω		40	70	1
Fall Time	t _f	Ů		9	18	1
Turn-On Delay Time	t _{d(on)}			48	80	ns
Rise Time	t _r	V_{DD} = - 15 V, R_L = 1.5 Ω		92	160	
Turn-Off DelayTime	t _{d(off)}	$I_D \cong -10 \text{ A}, V_{GEN} = -4.5 \text{ V}, R_g = 1 \Omega$		34	60	
Fall Time	t _f	Č		19	35	
Drain-Source Body Diode Characteris	tics					
Continous Source-Drain Diode Current	I _S	T _C = 25 °C			- 4.1	
Pulse Diode Forward Current	I _{SM}	-			- 40	A
Body Diode Voltage	V _{SD}	I _S = - 3 A, V _{GS} = 0 V		- 0.75	- 1.2	V
Body Diode Reverse Recovery Time	t _{rr}	3 , 63 -		27	45	ns
Body Diode Reverse Recovery Charge	Q _{rr}	10 A 31/44 100 A/45 T 05 00		16	27	nC
Reverse Recovery Fall Time	t _a	$I_F = -10 \text{ A}, \text{ dI/dt} = 100 \text{ A/}\mu\text{s}, T_J = 25 \text{ °C}$		12		ns
Reverse Recovery Rise Time	t _b			15		

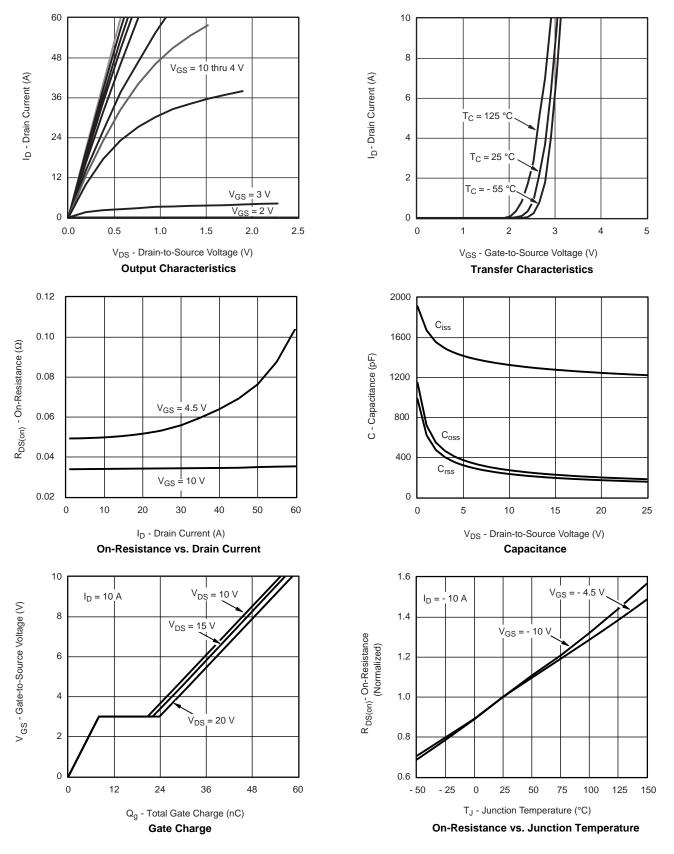
Notes:

- a. Pulse test; pulse width $\leq 300~\mu s,$ duty cycle $\leq 2~\%.$
- b. Guaranteed by design, not subject to production testing.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

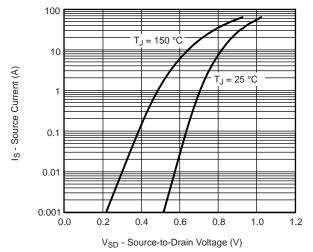


TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

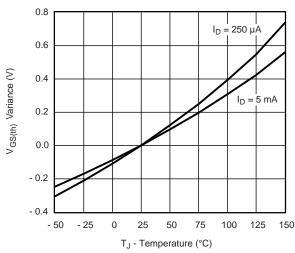




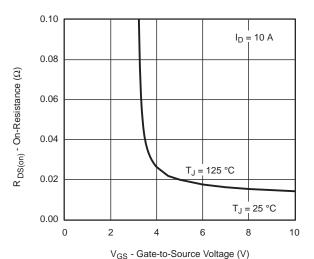
TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



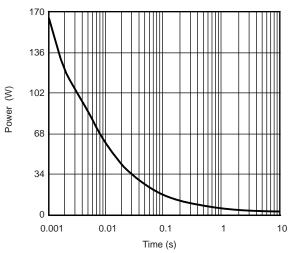
Source-Drain Diode Forward Voltage



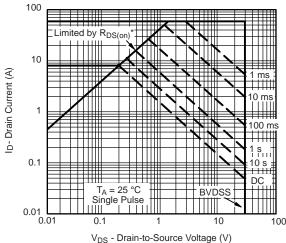
Threshold Voltage



On-Resistance vs. Gate-to-Source Voltage



Single Pulse Power, Junction-to-Ambient

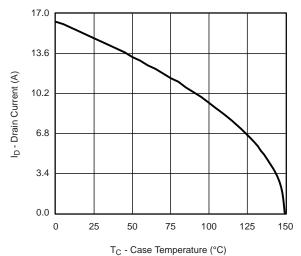


* V_{GS} > minimum V_{GS} at which R_{DS(on)} is specified

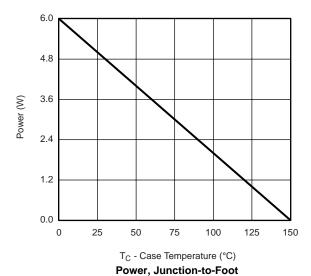
Safe Operating Area

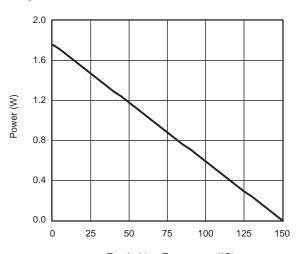


MOSFET TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



Current Derating*





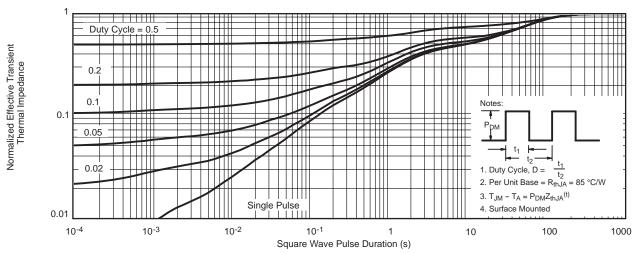
T_A - Ambient Temperature (°C)

Power Derating, Junction-to-Ambient

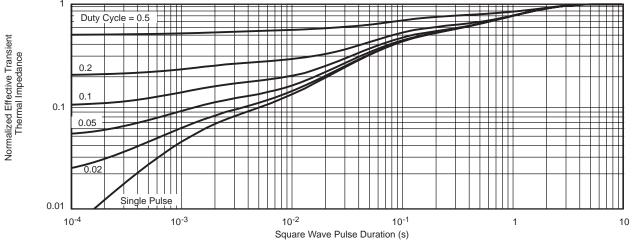
^{*} The power dissipation P_D is based on $T_{J(max)}$ = 150 °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package



TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



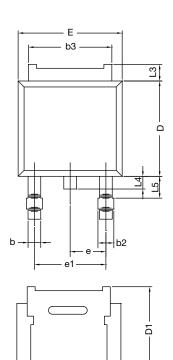
Normalized Thermal Transient Impedance, Junction-to-Ambient



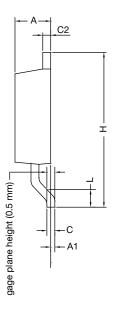
Normalized Thermal Transient Impedance, Junction-to-Foot



TO-252AA CASE OUTLINE



E1



	MILLIMETERS		INC	HES		
DIM.	MIN.	MAX.	MIN.	MAX.		
А	2.18	2.38	0.086	0.094		
A1	-	0.127	-	0.005		
b	0.64	0.88	0.025	0.035		
b2	0.76	1.14	0.030	0.045		
b3	4.95	5.46	0.195	0.215		
С	0.46	0.61	0.018	0.024		
C2	0.46	0.89	0.018	0.035		
D	5.97	6.22	0.235	0.245		
D1	5.21	-	0.205	-		
Е	6.35	6.73	0.250	0.265		
E1	4.32	-	0.170	-		
Н	9.40	10.41	0.370	0.410		
е	2.28	BSC	0.090	BSC		
e1	4.56	6 BSC 0.180 BS		BSC		
L	1.40	1.78	0.055	0.070		
L3	0.89	1.27	0.035	0.050		
L4	-	1.02	-	0.040		
L5	1.14	1.52	0.045	0.060		
ECN: X12-0247-Rev. M. 24-Dec-12						

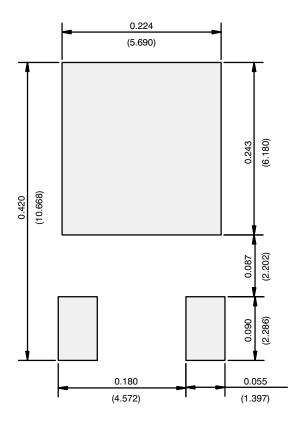
ECN: X12-0247-Rev. M, 24-Dec-12 DWG: 5347

Note

• Dimension L3 is for reference only.



RECOMMENDED MINIMUM PADS FOR DPAK (TO-252)



Recommended Minimum Pads Dimensions in Inches/(mm)



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